

Regarding Application to Stabilize Polishing Rate in a Short Time After S Pad Pad Replacement

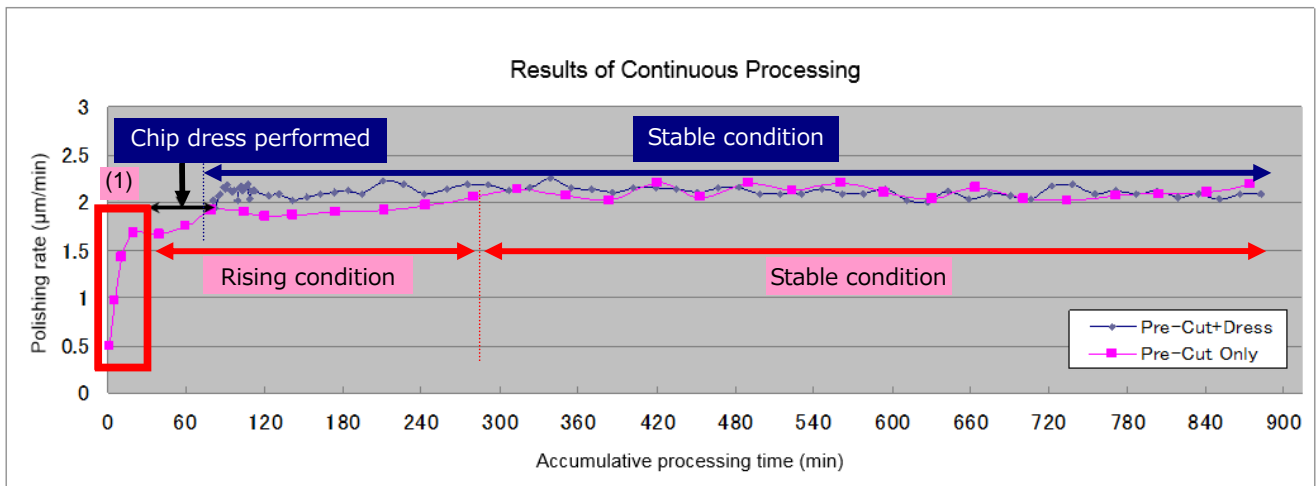
Notice

In order to maintain a stable polishing rate, DISCO recommends performing pre-cut after S Pad pad replacement.

With existing pre-cut, a polishing rate of 1.5 $\mu\text{m}/\text{min}$ is achieved by polishing 4 bare wafers (see image "(1)" below) after pad replacement (Pre-Cut Only in image below). However, after that, the polishing rate tends to rise for 270 minutes of polishing, finally stabilizing at 2 $\mu\text{m}/\text{min}$.

In response to the need for a stable polishing rate, we have now developed an application to achieve a polishing rate of 2.0 $\mu\text{m}/\text{min}$ or more starting from the first processed wafer by adding a die dressing process after the existing pre-cut (Pre-Cut+Dress in image below).

Note: The results differ depending on the recipe and other parameters. For details, please contact DISCO.



Inquiry

If you have any further questions, please contact your DISCO sales representative or your nearest DISCO service office.